



Product/Process Change Notice - PCN 16_0248 Rev. -

Analog Devices, Inc. Three Technology Way Norwood, Massachusetts 02062-9106

This notice is to inform you of a change that will be made to certain ADI products (see Appendix A) that you may have purchased in the last 2 years. **Any inquiries or requests with this PCN (additional data or samples) must be sent to ADI within 30 days of publication date.** ADI contact information is listed below.

PCN Title: Assembly Transfer of ADP2118 LFCSP Products to ASE Korea
Publication Date: 21-Oct-2016
Effectivity Date: 21-Oct-2016 *(the earliest date that a customer could expect to receive changed material)*

Revision Description:

Initial Release

Description Of Change

ADI is transferring to subcontractor ASE Korea for assembly manufacturing of select LFCSP products. ADI has qualified ASE Korea's BOM (Bill of Materials). The mold compound is changing from Sumitomo G770 to Sumitomo G700. The package outline exposed pad dimensions are changing for 4x4mm 16LD. See POD attachment for details.

Reason For Change

ADI's current Assembly supplier STATS ChipPAC China is relocating their factory by end of September 2017. In this regard, the affected products currently assembled in that facility will be transferred to ASE Korea to ensure continuous supply of products. There is now a raw material supply issue due to a natural disaster.

ADI's assembly subcontractors manufacture products using Analog Devices specified manufacturing flows, materials, process controls and monitors, ensuring the same level of quality and reliability on products they receive from the new site.

Impact of the change (positive or negative) on fit, form, function & reliability

There will be no impact on the form, fit, function and reliability of the devices.

Product Identification *(this section will describe how to identify the changed material)*

The parts that will be assembled from the transfer will be identified by assembly lot and the country of origin.

Summary of Supporting Information

Qualification has been performed per Industry Standard Test Methods. See attached Qualification Results Summary.

Supporting Documents

Attachment 1: Type: Qualification Results Summary
ADI_PCN_16_0248_Rev_-_Qual Results Summary for LFCSP.pdf

Attachment 2: Type: Detailed Change Description
ADI_PCN_16_0248_Rev_-_BOM Change Description.pptx

Attachment 3: Type: Detailed Change Description
ADI_PCN_16_0248_Rev_-_POD Change Description.pptx

For questions on this PCN, please send an email to the regional contacts below or contact your local ADI sales representatives.

Americas: PCN_Americas@analog.com

Europe: PCN_Europe@analog.com

Japan: PCN_Japan@analog.com

Rest of Asia: PCN_ROA@analog.com

Appendix A - Affected ADI Models

Added Parts On This Revision - Product Family / Model Number (8)

ADP2118 / ADP21180001CPZR7	ADP2118 / ADP2118ACPZ-1.0-R7	ADP2118 / ADP2118ACPZ-1.2-R7	ADP2118 / ADP2118ACPZ-1.5-R7	ADP2118 / ADP2118ACPZ-1.8-R7
ADP2118 / ADP2118ACPZ-2.5-R7	ADP2118 / ADP2118ACPZ-3.3-R7	ADP2118 / ADP2118ACPZ-R7		

Appendix B - Revision History

Rev	Publish Date	Effectivity Date	Rev Description
Rev. -	21-Oct-2016	21-Oct-2016	Initial Release

Analog Devices, Inc.

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